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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f52104bdfl-30

Table 1.1 Outline of Specifications (5 / 5)

Classification	Module/Function	Description
Packages	Chip version A	100-pin TFLGA (PTLG0100JA-A) 7 × 7 mm, 0.65-mm pitch 100-pin LQFP (PLQP0100KB-A) 14 × 14 mm, 0.5-mm pitch 80-pin LQFP (PLQP0080KB-A) 12 × 12 mm, 0.5-mm pitch 64-pin LQFP (PLQP0064KB-A) 10 × 10 mm, 0.5-mm pitch
	Chip version B	145-pin TFLGA (PTLG0145KA-A) 7 × 7 mm, 0.5-mm pitch 100-pin TFLGA (PTLG0100JA-A) 7 × 7 mm, 0.65-mm pitch 100-pin TFLGA (PTLG0100KA-A) 5.5 × 5.5 mm, 0.5-mm pitch 64-pin TFLGA (PTLG0064JA-A) 6 × 6 mm, 0.65-mm pitch 144-pin LQFP (PLQP0144KA-A) 20 × 20 mm, 0.5-mm pitch 100-pin LQFP (PLQP0100KB-A) 14 × 14 mm, 0.5-mm pitch 80-pin LQFP (PLQP0080KB-A) 12 × 12 mm, 0.5-mm pitch 80-pin LQFP (PLQP0080JA-A) 14 × 14 mm, 0.65-mm pitch 64-pin LQFP (PLQP0064KB-A) 10 × 10 mm, 0.5-mm pitch 64-pin LQFP (PLQP0064GA-A) 14 × 14 mm, 0.8-mm pitch 48-pin LQFP (PLQP0048KB-A) 7 × 7 mm, 0.5-mm pitch 69-pin WLBGA (SWBG0069LA-A) 3.91 × 4.26mm, 0.40-mm pitch
	Chip version C	100-pin TFLGA (PTLG0100JA-A) 7 × 7 mm, 0.65-mm pitch 100-pin LQFP (PLQP0100KB-A) 14 × 14 mm, 0.5-mm pitch 80-pin LQFP (PLQP0080KB-A) 12 × 12 mm, 0.5-mm pitch 80-pin LQFP (PLQP0080JA-A) 14 × 14 mm, 0.65-mm pitch 64-pin LQFP (PLQP0064KB-A) 10 × 10 mm, 0.5-mm pitch 64-pin LQFP (PLQP0064GA-A) 14 × 14 mm, 0.8-mm pitch
On-chip debugging system		E1 emulator (FINE interface)

Note 1. In chip version A of the part numbers below, port P17 is not 5 V tolerant. Therefore there is only one port in these products.
R5F52108ADFM, R5F52107ADFM, R5F52106ADFM, and R5F52105ADFM

Note 2. Please contact Renesas Electronics sales office for derating of operation under Ta = +85°C to +105°C. Derating is the systematic reduction of load for the sake of improved reliability.

Table 1.6 List of Products Chip Version C: D Version (Ta = –40 to +85°C)

Group	Part No.	Orderable Part No.	Package	ROM Capacity	RAM Capacity	E2 DataFlash	Operating Frequency (Max.)	Operating Temperature
RX210	R5F52108CDFP	R5F52108CDFP#30	PLQP0100KB-A	512 Kbytes	64 Kbytes	8 Kbytes	50 MHz	–40 to +85°C
	R5F52108CDFN	R5F52108CDFN#30	PLQP0080KB-A					
	R5F52108CDFM	R5F52108CDFM#30	PLQP0064KB-A					
	R5F52108CDLJ	R5F52108CDLJ#U0	PTLG0100JA-A					
	R5F52108CDFF	R5F52108CDFF#V0	PLQP0080JA-A					
	R5F52108CDFK	R5F52108CDFK#30	PLQP0064GA-A					
	R5F52107CDFP	R5F52107CDFP#30	PLQP0100KB-A	384 Kbytes				
	R5F52107CDFN	R5F52107CDFN#30	PLQP0080KB-A					
	R5F52107CDFM	R5F52107CDFM#30	PLQP0064KB-A					
	R5F52107CDLJ	R5F52107CDLJ#U0	PTLG0100JA-A					
	R5F52107CDFF	R5F52107CDFF#V0	PLQP0080JA-A					
	R5F52107CDFK	R5F52107CDFK#30	PLQP0064GA-A					

Note: • Orderable part numbers are current as of when this manual was published. Please make sure to refer to the relevant product page on the Renesas website for the latest part numbers.

Table 1.7 List of Products Chip Version C: G Version (Ta = –40 to +105°C)

Group	Part No.	Orderable Part No.	Package	ROM Capacity	RAM Capacity	E2 DataFlash	Operating Frequency (Max.)	Operating Temperature
RX210	R5F52108CGFP	R5F52108CGFP#30	PLQP0100KB-A	512 Kbytes	64 Kbytes	8 Kbytes	50 MHz	–40 to +105°C
	R5F52108CGFN	R5F52108CGFN#30	PLQP0080KB-A					
	R5F52108CGFM	R5F52108CGFM#30	PLQP0064KB-A					
	R5F52108CGFF	R5F52108CGFF#V0	PLQP0080JA-A					
	R5F52108CGFK	R5F52108CGFK#30	PLQP0064GA-A					
	R5F52107CGFP	R5F52107CGFP#30	PLQP0100KB-A	384 Kbytes				
	R5F52107CGFN	R5F52107CGFN#30	PLQP0080KB-A					
	R5F52107CGFM	R5F52107CGFM#30	PLQP0064KB-A					
	R5F52107CGFF	R5F52107CGFF#V0	PLQP0080JA-A					
	R5F52107CGFK	R5F52107CGFK#30	PLQP0064GA-A					

Note: • Please contact Renesas Electronics sales office for derating of operation under Ta = +85°C to +105°C. Derating is the systematic reduction of load for the sake of improved reliability.

Note: • Orderable part numbers are current as of when this manual was published. Please make sure to refer to the relevant product page on the Renesas website for the latest part numbers.

Table 1.10 List of Pins and Pin Functions (144-Pin LQFP) (1 / 4)

Pin No.	Power Supply, Clock, System Control	I/O Port	External Bus	Timers (MTU, TMR, POE)	Communications (SCIc, SCId, RSPI, RIIC)	Others
1	AVSS0					
2		P05				DA1
3	VREFH					
4		P03				DA0
5	VREFL					
6		P02		TMCI1	SCK6	
7		P01		TMCI0	RXD6/SMISO6/SSCL6	
8		P00		TMRI0	TXD6/SMOSI6/SSDA6	
9		PF5				IRQ4
10	NC					
11		PJ5				
12	VSS					
13		PJ3		MTIOC3C	CTS6#/RTS6#/SS6#/ CTS0#/RTS0#/SS0#	
14	VCL					
15		PJ1		MTIOC3A		
16	MD					FINED
17	XCIN					
18	XCOUT					
19	RES#					
20	XTAL	P37				
21	VSS					
22	EXTAL	P36				
23	VCC					
24		P35				NMI
25		P34		MTIOC0A/TMCI3/ POE2#	SCK6/SCK0	IRQ4
26		P33		MTIOC0D/TMRI3/ POE3#/TIOCD0	RXD6/SMISO6/SSCL6/ RXD0/SMISO0/SSCL0	IRQ3-DS
27		P32		MTIOC0C/TMO3/ TIOCC0	TXD6/SMOSI6/SSDA6/ TXD0/SMOSI0/SSDA0	IRQ2-DS/RTCOUT/ RTCIC2
28		P31		MTIOC4D/TMCI2	CTS1#/RTS1#/SS1#	IRQ1-DS/RTCIC1
29		P30		MTIOC4B/TMRI3/ POE8#	RXD1/SMISO1/SSCL1	IRQ0-DS/RTCIC0
30		P27	CS3#	MTIOC2B/TMCI3	SCK1	
31		P26	CS2#	MTIOC2A/TMO1	TXD1/SMOSI1/SSDA1/ CTS3#/RTS3#/SS3#	
32		P25	CS1#	MTIOC4C/MTCLKB/ TIOCA4	RXD3/SMISO3/SSCL3	ADTRG0#
33		P24	CS0#	MTIOC4A/MTCLKA/ TMRI1/TIOCB4	SCK3	
34		P23		MTIOC3D/MTCLKD/ TIOCD3	CTS0#/RTS0#/SS0#/ TXD3/SMOSI3/SSDA3	
35		P22		MTIOC3B/MTCLKC/ TMO0/TIOCC3	SCK0	
36		P21		MTIOC1B/TMCI0/ TIOCA3	RXD0/SMISO0/SSCL0	
37		P20		MTIOC1A/TMRI0/ TIOCB3	TXD0/SMOSI0/SSDA0	
38		P17		MTIOC3A/MTIOC3B/ TMO1/POE8#/TIOCB0/ TCLKD	SCK1/MISOA/SDA-DS/ TXD3/SMOSI3/SSDA3	IRQ7
39		P87		TIOCA2		

Table 1.13 List of Pins and Pin Functions (80-Pin LQFP) (1 / 2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TMR, POE)	Communications (SCIc, SCId, RSPI, RIIC)	Others
1	VREFH				
2		P03			DA0
3	VREFL				
4	VCL				
5		PJ1	MTIOC3A		
6	MD				FINED
7	XCIN				
8	XCOUT				
9	RES#				
10	XTAL	P37			
11	VSS				
12	EXTAL	P36			
13	VCC				
14		P35			NMI
15		P34	MTIOC0A/TMCI3/POE2#	SCK6	IRQ4
16		P32	MTIOC0C/TMO3	TXD6/SMOSI6/SSDA6	IRQ2-DS/RTCOUT/ RTCIC2
17		P31	MTIOC4D/TMCI2	CTS1#/RTS1#/SS1#	IRQ1-DS/RTCIC1
18		P30	MTIOC4B/TMRI3/POE8#	RXD1/SMISO1/SSCL1	IRQ0-DS/RTCIC0
19		P27	MTIOC2B/TMCI3	SCK1	
20		P26	MTIOC2A/TMO1	TXD1/SMOSI1/SSDA1	
21		P21	MTIOC1B/TMCI0	RXD0/SSCL0	
22		P20	MTIOC1A/TMRI0	TXD0/SSDA0	
23		P17	MTIOC3A/MTIOC3B/TMO1/ POE8#	SCK1/MISOA/ SDA-DS	IRQ7
24		P16	MTIOC3C/MTIOC3D/TMO2	TXD1/SMOSI1/SSDA1/MOSIA/ SCL-DS	IRQ6/RTCOUT/ ADTRG0#
25		P15	MTIOC0B/MTCLKB/TMCI2	RXD1/SMISO1/SSCL1	IRQ5
26		P14	MTIOC3A/MTCLKA/TMRI2	CTS1#/RTS1#/SS1#	IRQ4
27		P13	MTIOC0B/TMO3	SDA	IRQ3
28		P12	TMCI1	SCL	IRQ2
29		PH3	TMCI0		
30		PH2	TMRI0		IRQ1
31		PH1	TMO0		IRQ0
32		PH0			CACREF
33		P55	MTIOC4D/TMO3		
34		P54	MTIOC4B/TMCI1		
35		PC7	MTIOC3A/TMO2/MTCLKB	TXD8/SMOSI8/SSDA8/MISOA	CACREF
36		PC6	MTIOC3C/MTCLKA/TMCI2	RXD8/SMISO8/SSCL8/MOSIA	
37		PC5	MTIOC3B/MTCLKD/TMRI2	SCK8/RSPCKA	
38		PC4	MTIOC3D/MTCLKC/TMCI1/ POE0#	SCK5/CTS8#/RTS8#/SS8#/ SSLA0	
39		PC3	MTIOC4D	TXD5/SMOSI5/SSDA5	
40		PC2	MTIOC4B	RXD5/SMISO5/SSCL5/SSLA3	
41		PB7	MTIOC3B	TXD9/SMOSI9/SSDA9	
42		PB6	MTIOC3D	RXD9/SMISO9/SSCL9	
43		PB5	MTIOC2A/MTIOC1B/TMRI1/ POE1#	SCK9	
44		PB4		CTS9#/RTS9#/SS9#	

Table 1.13 List of Pins and Pin Functions (80-Pin LQFP) (2 / 2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TMR, POE)	Communications (SCIc, SCId, RSPI, RIIC)	Others
45		PB3	MTIOC0A/MTIOC4A/TMO0/ POE3#	SCK6	
46		PB2		CTS6#/RTS6#/SS6#	
47		PB1	MTIOC0C/MTIOC4C/TMCI0	TXD6/SMOSI6/SSDA6	IRQ4-DS
48	VCC				
49		PB0	MTIC5W	RXD6/SMISO6/SSCL6/RSPCKA	
50	VSS				
51		PA6	MTIC5V/MTCLKB/TMCI3/ POE2#	CTS5#/RTS5#/SS5#/MOSIA	
52		PA5		RSPCKA	
53		PA4	MTIC5U/MTCLKA/TMRI0	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5-DS/CVREFB1
54		PA3	MTIOC0D/MTCLKD	RXD5/SMISO5/SSCL5	IRQ6-DS/CMPB1
55		PA2		RXD5/SMISO5/SSCL5/SSLA3	
56		PA1	MTIOC0B/MTCLKC	SCK5/SSLA2	CVREFA
57		PA0	MTIOC4A	SSLA1	CACREF
58		PE5	MTIOC4C/MTIOC2B		IRQ5/AN013
59		PE4	MTIOC4D/MTIOC1A		AN012/CMPA2
60		PE3	MTIOC4B/POE8#	CTS12#/RTS12#/SS12#	AN011/CMPA1
61		PE2	MTIOC4A	RXD12/RXDX12/SMISO12/ SSCL12	IRQ7-DS/AN010/ CVREFB0
62		PE1	MTIOC4C	TXD12/TXDX12/SIOX12/ SMOSI12/SSDA12	AN009/CMPB0
63		PE0		SCK12	AN008
64		PD2	MTIOC4D		IRQ2
65		PD1	MTIOC4B		IRQ1
66		PD0			IRQ0
67		P47			AN007
68		P46			AN006
69		P45			AN005
70		P44			AN004
71		P43			AN003
72		P42			AN002
73		P41			AN001
74	VREFL0				
75		P40			AN000
76	VREFH0				
77	AVCC0				
78		P07			ADTRG0#
79	AVSS0				
80		P05			DA1

Note: • Pin names to which –DS is appended are for pins that can be used to trigger release from deep software standby mode.

4. I/O Registers

This section gives information on the on-chip I/O register addresses and bit configuration. The information is given as shown below. Notes on writing to registers are also given at the end.

(1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to module symbols.
- Numbers of cycles for access indicate numbers of cycles of the given base clock.
- Among the internal I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.

(2) Notes on writing to I/O registers

When writing to an I/O register, the CPU starts executing the subsequent instruction before completing I/O register write. This may cause the subsequent instruction to be executed before the post-update I/O register value is reflected on the operation.
As described in the following examples, special care is required for the cases in which the subsequent instruction must be executed after the post-update I/O register value is actually reflected.

[Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERn of the ICU (interrupt request enable bit) cleared to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

(a) Write to an I/O register.
(b) Read the value from the I/O register to a general register.
(c) Execute the operation using the value read.
(d) Execute the subsequent instruction.

[Instruction examples]

- Byte-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.B  #SFR_DATA, [R1]
CMP    [R1].UB, R1
;; Next process
```

- Word-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.W  #SFR_DATA, [R1]
CMP    [R1].W, R1
;; Next process
```

Table 4.1 List of I/O Registers (Address Order) (22 / 29)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles: ICLK ≥ PCLK	Number of Access Cycles: ICLK < PCLK
0008 C000h	PORT0	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C001h	PORT1	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C002h	PORT2	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C003h	PORT3	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C004h	PORT4	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C005h	PORT5	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C006h	PORT6	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C007h	PORT7	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C008h	PORT8	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C009h	PORT9	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C00Ah	PORTA	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C00Bh	PORTB	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C00Ch	PORTC	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C00Dh	PORTD	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C00Eh	PORTE	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C00Fh	PORTF	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C011h	PORTH	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C012h	PORTJ	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C013h	PORTK	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C014h	PORTL	Port direction register	PDR	8	8	2, 3 PCLKB	2 ICLK
0008 C020h	PORT0	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C021h	PORT1	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C022h	PORT2	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C023h	PORT3	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C024h	PORT4	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C025h	PORT5	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C026h	PORT6	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C027h	PORT7	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C028h	PORT8	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C029h	PORT9	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C02Ah	PORTA	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C02Bh	PORTB	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C02Ch	PORTC	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C02Eh	PORTE	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C02Fh	PORTF	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C031h	PORTH	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C032h	PORTJ	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C033h	PORTK	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C034h	PORTL	Port output data register	PODR	8	8	2, 3 PCLKB	2 ICLK
0008 C040h	PORT0	Port input data register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 C041h	PORT1	Port input data register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing

Table 4.1 List of I/O Registers (Address Order) (24 / 29)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles: ICLK ≥ PCLK	Number of Access Cycles: ICLK < PCLK
0008 C04Ch	PORTC	Port input data register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 C04Dh	PORTD	Port input data register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 C04Eh	PORTE	Port input data register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 C04Fh	PORTF	Port input data register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 C051h	PORTH	Port input data register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 C052h	PORTJ	Port input data register	PIDR	8	8	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 C053h	PORTK	Port input data register	PIDR	8	8	2, 3 PCLKB	2 ICLK
0008 C054h	PORTL	Port input data register	PIDR	8	8	2, 3 PCLKB	2 ICLK
0008 C060h	PORT0	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C061h	PORT1	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C062h	PORT2	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C063h	PORT3	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C064h	PORT4	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C065h	PORT5	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C066h	PORT6	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C067h	PORT7	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C068h	PORT8	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C069h	PORT9	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C06Ah	PORTA	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C06Bh	PORTB	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C06Ch	PORTC	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C06Dh	PORTD	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C06Eh	PORTE	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C06Fh	PORTF	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C071h	PORTH	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C072h	PORTJ	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C073h	PORTK	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK
0008 C074h	PORTL	Port mode register	PMR	8	8	2, 3 PCLKB	2 ICLK

5. Electrical Characteristics

5.1 Absolute Maximum Ratings

Table 5.1 Absolute Maximum Ratings

Conditions: VSS = AVSS0 = VREFL = VREFL0 = 0 V

Item	Symbol	Value	Unit
Power supply voltage	VCC	–0.3 to +6.5	V
Input voltage (except for ports for 5 V tolerant*1)	V_{in}	–0.3 to VCC +0.3*3	V
Input voltage (ports for 5 V tolerant*1)	V_{in}	–0.3 to +6.5	V
Reference power supply voltage	VREFH, VREFH0	–0.3 to VCC +0.3*3	V
Analog power supply voltage	AVCC0*2	–0.3 to +6.5	V
Analog input voltage	V_{AN}	–0.3 to VCC +0.3*3	V
Operating temperature	T_{opr}	–40 to +105	°C
Storage temperature	T_{stg}	–55 to +125	°C

Caution: Permanent damage to the LSI may result if absolute maximum ratings are exceeded.

To preclude any malfunctions due to noise interferences, insert capacitors of high frequency characteristics between the VCC and VSS pins, between the AVCC0 and AVSS0 pins, and between the VREFH0 and VREFL0 pins. Place capacitors of 0.1 µF or so as close to every power pin and use the shortest and heaviest possible traces.

Connect the VCL pin to a VSS pin via a 0.1 µF (±20% accuracy) capacitor. The capacitor must be placed as close to the pin as possible.

Note 1. Ports 12, 13, 16, and 17 are 5 V tolerant.

Note 2. Connect AVCC0 to VCC. When neither the A/D converter nor the D/A converter is in use, do not leave the AVCC0, VREFH, VREFH0, AVSS0, VREFL, and VREFL0 pins open. Connect the AVCC0, VREFH, and VREFH0 pins to VCC, and the AVSS0, VREFL, and VREFL0 pins to VSS, respectively.

Note 3. The maximum value is 6.5 V.

Item					Symbol	Typ.	Max.	Unit	Test Conditions
Supply current*1	Low-speed operating mode 1	Normal operating mode	No peripheral operation*7	ICLK = 8 MHz	I_{CC}	2	—	mA	
				ICLK = 4 MHz		1.6	—		
				ICLK = 2 MHz		1.5	—		
			All peripheral operation: Normal*8	ICLK = 8 MHz		6	—		
				ICLK = 4 MHz		3.8	—		
				ICLK = 2 MHz		2.8	—		
			All peripheral operation: Max.*8	ICLK = 8 MHz		—	12		
				ICLK = 4 MHz		—	—		
				ICLK = 2 MHz		—	—		
		Sleep mode	No peripheral operation	ICLK = 8 MHz		1.5	—		
				ICLK = 4 MHz		1.4	—		
				ICLK = 2 MHz		1.3	—		
			All peripheral operation: Normal	ICLK = 8 MHz		3.6	—		
				ICLK = 4 MHz		2.7	—		
				ICLK = 2 MHz		2.2	—		
		All-module clock stop mode		ICLK = 8 MHz		1.4	—		
				ICLK = 4 MHz		1.3	—		
				ICLK = 2 MHz		1.2	—		
	Low-speed operating mode 2	Normal operating mode	No peripheral operation*9	ICLK = 32 kHz		0.021	—		
			All peripheral operation: Normal*10	ICLK = 32 kHz		0.05	—		
			All peripheral operation: Max.*10	ICLK = 32 kHz		—	3*11		
		Sleep mode	No peripheral operation	ICLK = 32 kHz		0.017	—		
			All peripheral operation: Normal	ICLK = 32 kHz		0.034	—		
		All-module clock stop mode				0.016	—		

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.
Note 2. Clock supply to the peripheral functions is stopped. This does not include BGO operation. The clock source is PLL and the VCO oscillation frequency is 64 MHz. BCLK, FCLK, and PCLK are set to divided by 64.
Note 3. Clock supply to the peripheral functions is stopped. This does not include BGO operation. The clock source is HOCO and the oscillation frequency is 40 MHz. BCLK, FCLK, and PCLK are set to divided by 64.
Note 4. Clocks are supplied to the peripheral functions. This does not include BGO operation. The clock source is PLL and the VCO oscillation frequency is 64 MHz. BCLK, FCLK, and PCLK are ICLK divided by 1.
Note 5. Clocks are supplied to the peripheral functions. This does not include BGO operation. The clock source is HOCO and the oscillation frequency is 40 MHz. BCLK, FCLK, and PCLK are ICLK divided by 1.
Note 6. This is the increase if data is programmed to or erasing from the ROM or E2 DataFlash during program execution.
Note 7. Clock supply to the peripheral functions is stopped. This does not include BGO operation. The clock source is HOCO and the oscillation frequency is 32 MHz. BCLK, FCLK, and PCLK are set to divided by 64.
Note 8. Clocks are supplied to the peripheral functions. This does not include BGO operation. The clock source is HOCO and the oscillation frequency is 32 MHz. BCLK, FCLK, and PCLK are ICLK divided by 1.
Note 9. Clock supply to the peripheral functions is stopped. This does not include BGO operation. The clock source is the sub oscillation circuit. BCLK, FCLK, and PCLK are set to divided by 64.
Note 10. Clocks are supplied to the peripheral functions. This does not include BGO operation. The clock source is the sub oscillation circuit. BCLK, FCLK, and PCLK are ICLK divided by 1.
Note 11. Value when the main clock continues oscillating at 12.5 MHz.

Table 5.25 DC Characteristics (24)

Conditions: VCC = AVCC0 = 1.62 to 5.5 V, VSS = AVSS0 = VREFL0 = 0 V, T_a = –40 to +105°C
The ripple voltage must meet the allowable ripple frequency $f_{r(VCC)}$ within the range between the VCC upper limit (5.5 V) and lower limit (1.62 V).
When VCC change exceeds VCC ±10%, the allowable voltage change rising/falling gradient dt/dVCC must be met.

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Allowable ripple frequency	$f_{r(VCC)}$	—	—	10	kHz	Figure 5.44 VCC × 0.1 < $V_{r(VCC)}$ ≤ VCC × 0.2
		—	—	1	MHz	Figure 5.44 VCC × 0.05 < $V_{r(VCC)}$ ≤ VCC × 0.1
		—	—	10	MHz	Figure 5.44 $V_{r(VCC)}$ ≤ VCC × 0.05
Allowable voltage change rising/ falling gradient	dt/dVCC	1.0	—	—	ms/V	When VCC change exceeds VCC ±10%

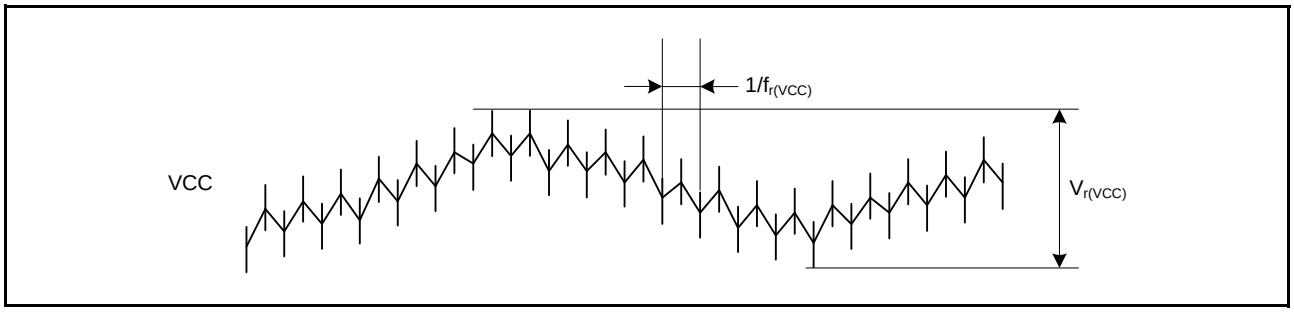

Figure 5.44 Ripple Waveform

Table 5.26 Permissible Output Currents (1)

Conditions: VCC = AVCC0 = 1.62 to 5.5 V, VSS = AVSS0 = VREFL = VREFL0 = 0 V, when total power (mW) < 1000 – 10 × Ta

Item			Symbol	Max.	Unit
Permissible output low current (average value per 1 pin)		Normal output mode	I_{OL}	4.0	mA
		High-drive output mode		8.0	
Permissible output low current (maximum value per 1 pin)		Normal output mode		4.0	mA
		High-drive output mode		8.0	
Permissible output low current (total)	Total of all output pins		ΣI_{OL}	80	mA
Permissible output high current (average value per 1 pin)		Normal output mode	I_{OH}	–4.0	mA
		High-drive output mode		–8.0	
Permissible output high current (maximum value per 1 pin)		Normal output mode		–4.0	mA
		High-drive output mode		–8.0	
Permissible output high current (total)	Total of all output pins		ΣI_{OH}	–80	mA

[Chip versions B and C]

Table 5.31 Output Values of Voltage (4)

Conditions: VCC = AVCC0 = 2.7 to 4.0 V, VSS = AVSS0 = VREFL = VREFL0 = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Max.	Unit	Test Conditions
Output low	All output pins (other than RIIC)	Normal output mode	V_{OL}	—	0.5	V	I_{OL} = 1.0 mA
		High-drive output mode		—	0.5		I_{OL} = 2.0 mA
	RIIC pins			—	0.4		I_{OL} = 3.0 mA
				—	0.6		I_{OL} = 6.0 mA
Output high	All output pins	Normal output mode	V_{OH}	VCC – 0.5	—	V	I_{OH} = –1.0 mA
		High-drive output mode		VCC – 0.5	—		I_{OH} = –2.0 mA

[Chip versions B and C]

Table 5.32 Output Values of Voltage (5)

Conditions: VCC = AVCC0 = 4.0 to 5.5 V, VSS = AVSS0 = VREFL = VREFL0 = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Max.	Unit	Test Conditions
Output low	All output pins (other than RIIC)	Normal output mode	V_{OL}	—	0.8	V	I_{OL} = 2.0 mA
		High-drive output mode		—	0.8		I_{OL} = 4.0 mA
	RIIC pins			—	0.4		I_{OL} = 3.0 mA
				—	0.6		I_{OL} = 6.0 mA
Output high	All output pins	Normal output mode	V_{OH}	VCC – 0.8	—	V	I_{OH} = –2.0 mA
		High-drive output mode		VCC – 0.8	—		I_{OH} = –4.0 mA

5.2.1 Standard I/O Pin Output Characteristics (1)

Figure 5.45 to Figure 5.49 show the characteristics when normal output is selected by the drive capacity control register.

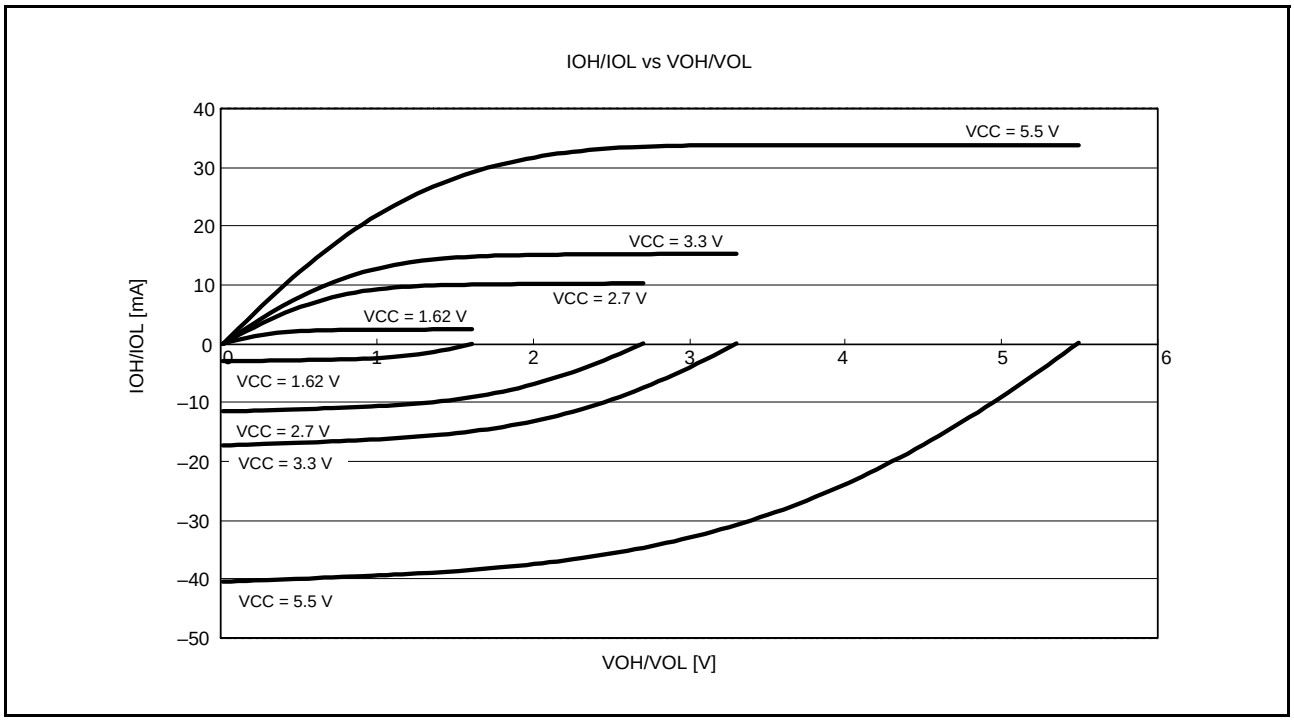

Figure 5.45 VOH/VOL and IOH/IOL Voltage Characteristics at Ta = 25°C when Normal Output is Selected (Reference Data)

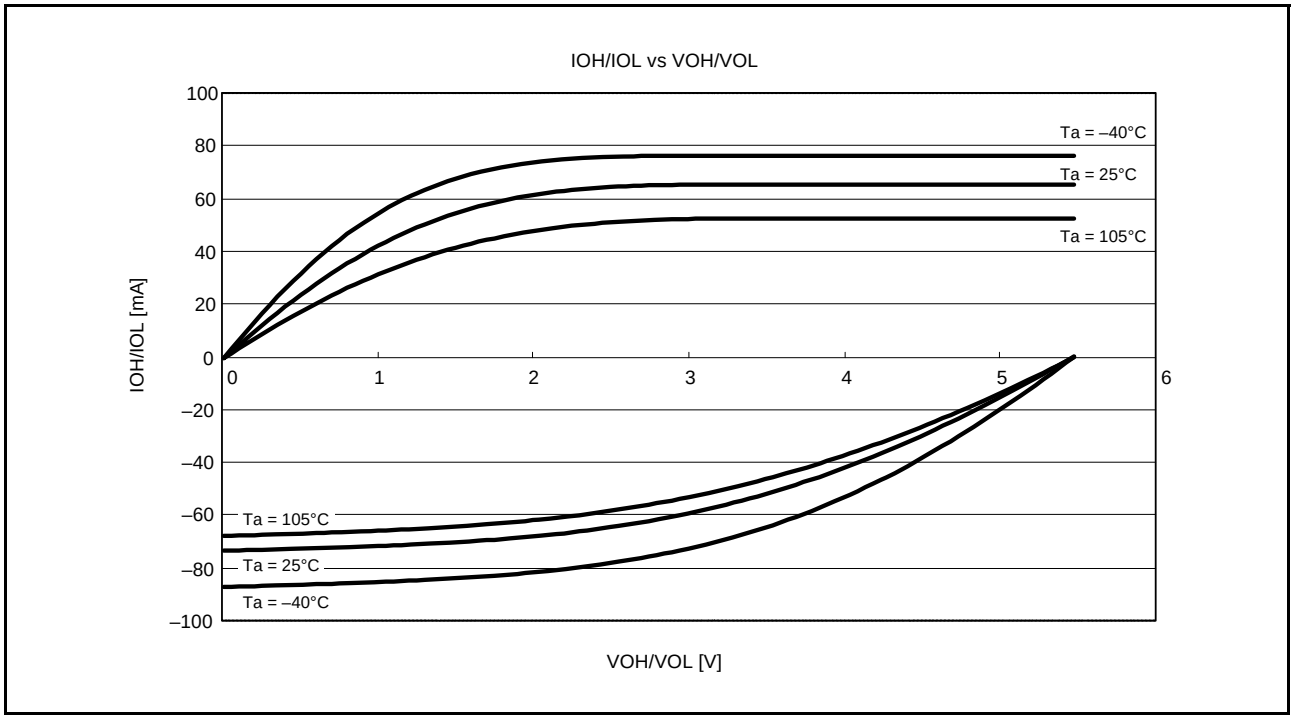

Figure 5.54 VOH/VOL and IOH/IOL Temperature Characteristics at VCC = 5.5 V when High-Drive Output is Selected (Reference Data)

Table 5.44 Clock Timing

Conditions: VCC = AVCC0 = 1.62 to 5.5 V, VSS = AVSS0 = VREFL = VREFL0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
EXTAL external clock input cycle time		t_{EXcyc}	50	—	—	ns	Figure 5.60
EXTAL external clock input high pulse width		t_{EXH}	20	—	—	ns	
EXTAL external clock input low pulse width		t_{EXL}	20	—	—	ns	
EXTAL external clock rising time		t_{EXr}	—	—	5	ns	
EXTAL external clock falling time		t_{EXf}	—	—	5	ns	
EXTAL external clock input wait time*1		t_{EXWT}	1	—	—	ms	
Main clock oscillator oscillation frequency*2		f_{MAIN}	1	—	20	MHz	
Main clock oscillation stabilization time (crystal)*2		$t_{MAINOSC}$	—	3	—	ms	Figure 5.61
Main clock oscillation stabilization time (ceramic resonator)*2		$t_{MAINOSC}$	—	50		µs	
Main clock oscillation stabilization wait time (crystal)*2		$t_{MAINOSCWT}$	—	6	—	ms	
Main clock oscillation stabilization wait time (ceramic resonator)*2		$t_{MAINOSCWT}$	—	100		µs	
LOCO clock cycle time		t_{cyc}	7.27	8	8.89	µs	
LOCO clock oscillation frequency*6		f_{LOCO}	112.5	125	137.5	kHz	
LOCO clock oscillation stabilization wait time		t_{LOCOWT}	—	—	20	µs	Figure 5.62
HOCO clock oscillation frequency*7		f_{HOCO}	31.680	32	32.320	MHz	Ta = 0 to 50°C
			36.495	36.864	37.233		
			39.600	40	40.400		
			49.500	50	50.500		
			31.520	32	32.480		Ta = -40 to 105°C
			36.311	36.864	37.417		
			39.400	40	40.600		
			49.250	50	50.750		
HOCO clock oscillation stabilization time 1		t_{HOCO1}	—	—	300	µs	Figure 5.63
HOCO clock oscillation stabilization time 2		t_{HOCO2}	—	—	175	µs	Figure 5.64
HOCO clock oscillation stabilization wait time		t_{HOCOWT}	—	—	350	µs	Figure 5.64
HOCO clock power supply stabilization time		t_{HOCOP}	—	—	350	µs	Figure 5.65
PLL input frequency		f_{PLLIN}	4	—	12.5	MHz	
PLL circuit oscillation frequency		f_{PLL}	50	—	100	MHz	
PLL clock oscillation stabilization time	PLL operation started after main clock oscillation has settled	t_{PLL1}	—	—	500	µs	Figure 5.66
PLL clock oscillation stabilization wait time		t_{PLLWT1}	1.5	—	—	ms	
PLL clock oscillation stabilization time*4	PLL operation started before main clock oscillation has settled	t_{PLL2}	—	3.5*3	—	ms	Figure 5.67
PLL clock oscillation stabilization wait time*4		t_{PLLWT2}	—	7	—	ms	
PLL clock power supply stabilization time (for chip version B only)		t_{PLLPW}	—	—	30	µs	Figure 5.68
Sub-clock oscillator oscillation frequency		f_{SUB}	—	32.768	—	kHz	
Sub-clock oscillation stabilization time*5		t_{SUBOSC}	2	—	—	s	Figure 5.69
Sub-clock oscillation stabilization wait time*5		$t_{SUBOSCWT}$	4	—	—	s	

Note 1. The time interval from the time P36 and P37 are configured for input and the main clock oscillator stopping bit (MOSCCR.MOSTP) is set to 0 (operating) until the clock becomes available.

[Chip version B]

Table 5.47 Timing of Recovery from Low Power Consumption Modes

Conditions: VCC = AVCC0 = 1.62 to 5.5 V, VSS = AVSS0 = VREFL = VREFL0 = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time after cancellation of software standby mode (HOCO power supplied) (SOFTCUT[2:0] bits = 000b)*1	Crystal resonator connected to main clock oscillator*2	Main clock oscillator operating	t_{SBYMC}	—	3	—	ms	Figure 5.72
		Main clock oscillator and PLL circuit operating	t_{SBYPC}	—	3.5	—	ms	
	External clock input to main clock oscillator	Main clock oscillator operating	t_{SBYEX}	10	—	—	µs	
		Main clock oscillator and PLL circuit operating	t_{SBYPE}	0.5	—	—	ms	
	Sub-clock oscillator operating		t_{SBYSC}	2*3	—	—	s	
	HOCO clock oscillator operating		t_{SBYHO}	—	—	500	µs	
	LOCO clock oscillator operating		t_{SBYLO}	—	—	90	µs	
Recovery time after cancellation of software standby mode (HOCO power not supplied) (SOFTCUT[2:0] bits = 110b)*1	Crystal resonator connected to main clock oscillator*2	Main clock oscillator operating	t_{SBYMC}	—	3	—	ms	Figure 5.72
		Main clock oscillator and PLL circuit operating	t_{SBYPC}	—	3.5	—	ms	
	External clock input to main clock oscillator	Main clock oscillator operating	t_{SBYEX}	40	—	—	µs	
		Main clock oscillator and PLL circuit operating	t_{SBYPE}	0.5	—	—	ms	
	Sub-clock oscillator operating		t_{SBYSC}	2*3	—	—	s	
	HOCO clock oscillator operating		t_{SBYHO}	—	—	1.2	ms	
	LOCO clock oscillator operating		t_{SBYLO}	—	—	90	µs	
Recovery time after cancellation of deep software standby mode			t_{DSBY}	—	—	8	ms	Figure 5.73
Wait time after cancellation of deep software standby mode			t_{DSBYWT}	—	—	0.8	ms	

Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source, and depends on the time set in the wait control registers corresponding to the oscillators.

Note 2. The indicated value is measured for an 8 MHz crystal resonator.

Note 3. When RCR3.RTCEN = 1, the time will be the time set in the SOSCWTCR register minus 2 s.

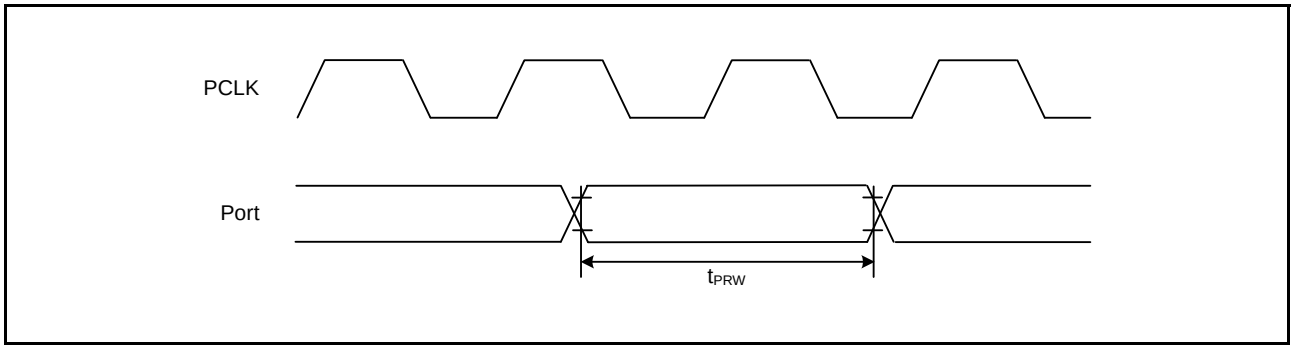

Figure 5.83 I/O Port Input Timing

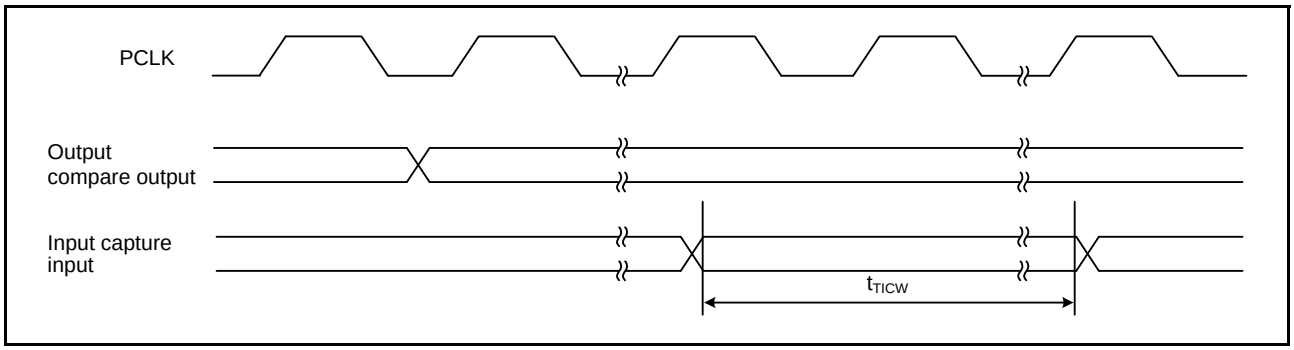

Figure 5.84 MTU/TPU Input/Output Timing

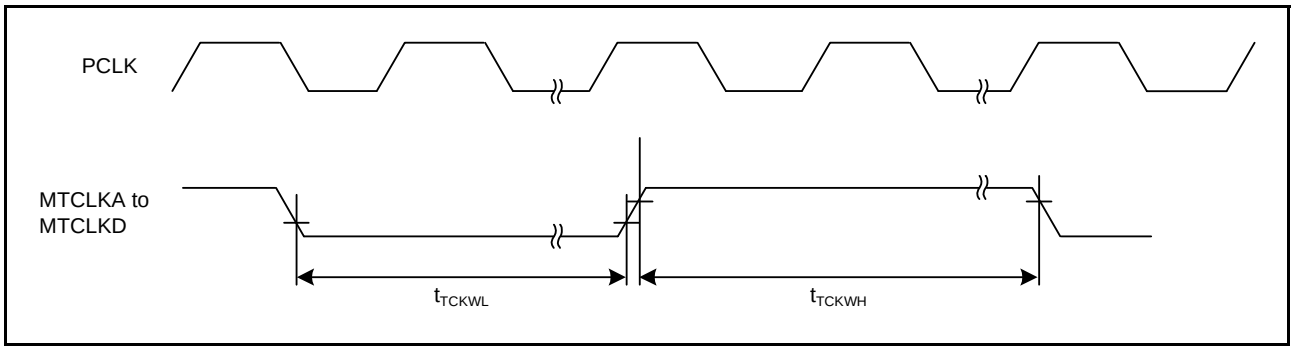

Figure 5.85 MTU/TPU Clock Input Timing

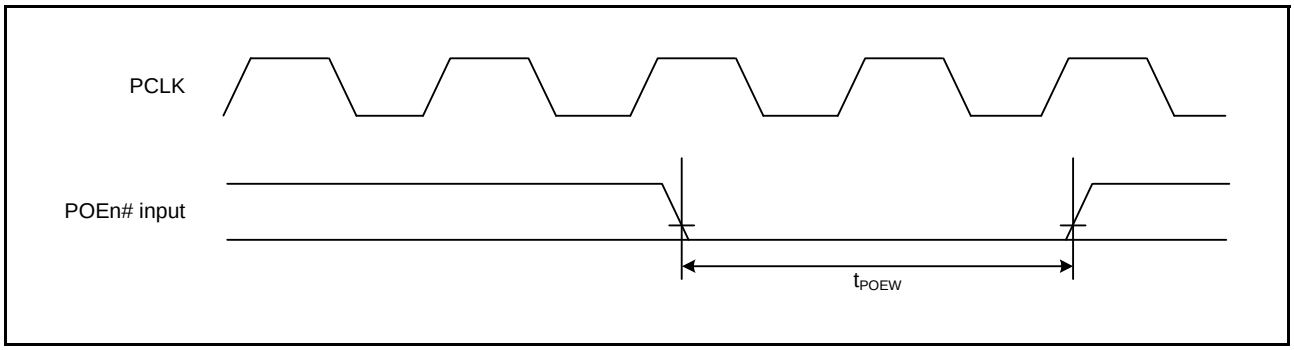

Figure 5.86 POE# Input Timing

Table 5.72 Power-on Reset Circuit and Voltage Detection Circuit Characteristics (2)

Conditions: VCC = AVCC0, VSS = AVSS0 = VREFL = VREFL0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Voltage detection circuit (LVD2)*1	V_{det2_0}	4.00	4.15	4.30	V	Figure 5.107 At falling edge VCC
		V_{det2_1}	3.85	4.00	4.15		
		V_{det2_2}	3.70	3.85	4.00		
		V_{det2_3}	3.55	3.70	3.85		
		V_{det2_4}	3.40	3.55	3.70		
		V_{det2_5}	3.25	3.40	3.55		
		V_{det2_6}	3.10	3.25	3.40		
		V_{det2_7}	2.95	3.10	3.25		
		V_{det2_8}	2.85	2.95	3.05		
		V_{det2_9}	2.70	2.80	2.90		
		V_{det2_A}	2.55	2.65	2.75		
		V_{det2_B}	2.40	2.50	2.60		
		V_{det2_C}	2.25	2.35	2.45		
		V_{det2_D}	2.10	2.20	2.30		
		V_{det2_E}	1.95	2.05	2.15		
		V_{det2_F}	1.80	1.90	2.00		
		V_{CMPA2}	1.18	1.33	1.48		EXVCCINP2 = 1
Internal reset time	Power-on reset time	t_{POR}	—	9	—	ms	Figure 5.104
	Voltage monitoring 0 reset time	t_{LVD0}	—	9	—		Figure 5.105
	Voltage monitoring 1 reset time	t_{LVD1}	—	1.4	—		Figure 5.106
	Voltage monitoring 2 reset time	t_{LVD2}	—	1.4	—		Figure 5.107
Minimum VCC down time*2		t_{VOFF}	200	—	—	µs	Figure 5.103
Response delay time		t_{det}	—	—	200	µs	Figure 5.104
LVD operation stabilization time (after LVD is enabled)		$Td_{(E-A)}$	—	—	15	µs	Figure 5.106 and Figure 5.107
Power-on reset enable time		$t_{W(POR)}$	1	—	—	ms	Figure 5.104 VCC = 0.9 V or lower
Hysteresis width (LVD1 and LVD2)		V_{LVH}	—	100	—	mV	When selection is from among VdetX_0 to 7.
			—	50	—		When selection is from among VdetX_8 to F.

Note: • These characteristics apply when noise is not superimposed on the power supply.

Note 1. # in the symbol Vdet2_# denotes the value of the LVDLVLR.LVD2LVL[3:0] bits.

Note 2. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det0}, V_{det1}, and V_{det2} for the POR/LVD.

[Chip versions A and C]

Table 5.77 ROM (Flash Memory for Code Storage) Characteristics (4) : middle-speed operating mode 1B

Conditions: VCC = AVCC0 = 1.62 to 3.6 V, VREFH = VREFH0 = AVCC0, VSS = AVSS0 = VREFL = VREFL0 = 0 V
Temperature range for the programming/erasure operation: T_a = –40 to +105°C

Item		Symbol	FCLK = 4 MHz			FCLK = 32 MHz*1			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time when N_{PEC} ≤ 100 times	2 bytes	t_{P2}	—	0.69	6.0	—	0.30	3.5	ms
	8 bytes	t_{P8}	—	0.69	6.0	—	0.30	3.5	
	128 bytes	t_{P128}	—	1.76	14.2	—	0.85	8.3	
Programming time when N_{PEC} > 100 times	2 bytes	t_{P2}	—	0.81	7.1	—	0.35	4.2	ms
	8 bytes	t_{P8}	—	0.81	7.6	—	0.35	4.5	
	128 bytes	t_{P128}	—	1.99	17.5	—	0.96	10	
Erasure time when N_{PEC} ≤ 100 times	2 Kbytes	t_{E2K}	—	24.5	113.7	—	19.0	46	ms
Erasure time when N_{PEC} > 100 times	2 Kbytes	t_{E2K}	—	29.8	225.8	—	23.2	90 (1000 times ≥ N_{PEC} > 100 times), 98 (10000 times ≥ N_{PEC} > 1000 times)	ms
Suspend delay time during programming (in programming/erasure priority mode)		t_{SPD}	—	—	1.7	—	—	1.6	ms
First suspend delay time during programming (in suspend priority mode)		t_{SPSD1}	—	—	220	—	—	120	µs
Second suspend delay time during programming (in suspend priority mode)		t_{SPSD2}	—	—	1.7	—	—	1.6	ms
Suspend delay time during erasing (in programming/erasure priority mode)		t_{SED}	—	—	1.7	—	—	1.6	ms
First suspend delay time during erasing (in suspend priority mode)		t_{SESD1}	—	—	220	—	—	120	µs
Second suspend delay time during erasing (in suspend priority mode)		t_{SESD2}	—	—	1.7	—	—	1.6	ms
FCU reset time		t_{FCUR}	20 µs or longer and FCLK × 6 or greater	—	—	20 µs or longer and FCLK × 6 or greater	—	—	µs

Note 1. The operating frequency is 20 MHz (max.) when the voltage is in the range from 1.62 V to less than 1.8 V.

5.11 E2 DataFlash Characteristics

[Chip version A]

Table 5.80 E2 DataFlash Characteristics (1)

Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
Reprogramming/erasure cycle*1	N_{DPEC}	100000	—	—	Times	
Data hold time	t_{DRP}	10*2	—	—	Year	

Note 1. The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 100000), erasing can be performed n times for each block. For instance, when 8-byte programming is performed 16 times for different addresses in 128-byte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).

Note 2. This result is obtained from reliability testing.

[Chip versions B and C]

Table 5.81 E2 DataFlash Characteristics (2)

Item		Symbol	Min.	Typ.	Max.	Unit	Conditions
Reprogramming/erasure cycle*1		N_{DPEC}	100000	—	—	Times	
Data hold time	After 100000 times of N_{DPEC}	t_{DRP}	30*2	—	—	Year	Ta = +85°C

Note 1. The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 100000), erasing can be performed n times for each block. For instance, when 8-byte programming is performed 16 times for different addresses in 128-byte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).

Note 2. This result is obtained from reliability testing.

[Chip version B]

Table 5.85 E2 DataFlash Characteristics (6)
: middle-speed operating modes 1B and 2B

Conditions: VCC = AVCC0 = 1.62 to 3.6 V, VREFH = VREFH0 = AVCC0, VSS = AVSS0 = VREFL = VREFL0 = 0 V
Temperature range for the programming/erasure operation: T_a = –40 to +105°C

Item		Symbol	FCLK = 4 MHz			FCLK = 32 MHz*1			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time when N_{DPEC} ≤ 100 times	2 bytes	t_{DP2}	—	0.28	5.1	—	0.20	2.8	ms
	8 bytes	t_{DP8}	—	0.32	6.0	—	0.22	3.2	
Programming time when N_{DPEC} > 100 times	2 bytes	t_{DP2}	—	0.36	7.6	—	0.25	4.2	ms
	8 bytes	t_{DP8}	—	0.40	8.8	—	0.28	4.5	
Erasure time when N_{DPEC} ≤ 100 times	128 bytes	t_{DE128}	—	4.8	32.4	—	4.1	12	ms
Erasure time when N_{DPEC} > 100 times	128 bytes	t_{DE128}	—	5.8	51.4	—	4.9	17	ms
Blank check time	2 bytes	t_{DBC2}	—	—	110	—	—	40	µs
	2 Kbytes	t_{DBC2K}	—	—	16.3	—	—	2.6	ms
Suspend delay time during programming (in programming/erasure priority mode)		t_{DSPD}	—	—	1.7	—	—	1.6	ms
First suspend delay time during programming (in suspend priority mode)		t_{DSPSD1}	—	—	220	—	—	120	µs
Second suspend delay time during programming (in suspend priority mode)		t_{DSPSD2}	—	—	1.7	—	—	1.6	ms
Suspend delay time during erasing (in programming/erasure priority mode)		t_{DSED}	—	—	1.7	—	—	1.6	ms
First suspend delay time during erasing (in suspend priority mode)		t_{DSESD1}	—	—	220	—	—	120	µs
Second suspend delay time during erasing (in suspend priority mode)		t_{DSESD2}	—	—	1.7	—	—	1.6	ms

Note 1. The operating frequency is 20 MHz (max.) when the voltage is in the range from 1.62 V to less than 1.8 V.